

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

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Title of
Invention

**MASK AND SUBSTRATE ALIGNMENT FOR SOLDER
BUMP PROCESS**

Application Number:

Confirmation Number:

First Named Applicant: Duane Allen

Attorney Docket Number: BUR920030027US1

Search string: (6327034 or 6274198 or 6030889 or 5324012 or 5296916 or 4915057 or 4755053 or 4746548 or 4544311 or 3647533 or 20010030747).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
/AS/	1	6327034	2001-12-04	Hoover et al			
/AS/	2	6274198	2001-08-14	Dautartas			
/AS/	3	6030889	2000-02-29	Aulicino et al			
/AS/	4	5324012	1994-06-28	Aoyama et al			
/AS/	5	5296916	1994-03-22	Kelly et al			
/AS/	6	4915057	1990-04-10	Boudreau et al			
/AS/	7	4755053	1988-07-05	Levinson et al			
/AS/	8	4746548	1988-05-24	Boudreau et al			
/AS/	9	4544311	1985-10-01	Husain			
/AS/	10	3647533	1972-03-07	Hicks			

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
/AS/	1	20010030747	2001-10-18	Hoover et al			

Signature

Examiner Name

Date

/Andre Stevenson/ (03/26/2008)

03/26/2008

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